

WHAT IS CLAIMED IS:

1. A liquid crystal display (LCD) device comprising:
 - a mold frame accommodating a lamp assembly, a reflector, a light guide, and a series of optical sheets;
 - 5 a bottom chassis installed at a bottom surface of said mold frame to support said lamp assembly, said reflector, said light guide, and said optical sheets;
 - an LCD panel positioned onto said optical sheets to display an image;
 - a printed circuit board (PCB) connected to said LCD panel via a tape
 - 10 carrier package (TCP), positioned to a rear surface of said bottom chassis by bending said TCP, and fixed to said bottom chassis by a fixing means;
 - a grounding member for providing a grounding path for an electromagnetic wave generated from said PCB, formed on a bottom surface portion of said PCB where a signal transmission pattern is not formed; and
 - 15 a top chassis assembled to said mold frame to support said LCD panel.
2. The LCD device according to Claim 1, wherein said grounding member comprises:
 - a metal film electrically connected to a grounding pattern of a top surface
 - 20 of said PCB and deposited to said portion where said signal transmission pattern is not formed, among said bottom surface of said PCB; and
 - a plurality of grounding protrusions protruded to a predetermined height

from said metal film.

3. The LCD device according to Claim 2, wherein a portion where said fixing means contacts and a portion where said grounding protrusions are formed are exposed by partially removing a solder resist film.

4. The LCD device according to Claim 2, wherein said grounding protrusions are made up of a lead.

5. The LCD device according to Claim 1, wherein said portion of said PCB where said fixing means is fixed in a predetermined area of each edges thereof.

6. A method for fabricating a grounding device comprising the steps of:
depositing a solder resist film to a bottom surface of a printed circuit board (PCB) over which a metal film is deposited and a signal transmission pattern is formed by a predetermined patterning process, in such a manner that a portion where a fixing means is fixed and a portion where said signal transmission pattern is not formed are exposed; and
forming a grounding protrusion by depositing a conductive substance to a predetermined height in said portion where said signal transmission pattern is not formed, to be electrically connected to said metal film.

7. The method according to Claim 6, wherein said step of depositing said solder resist film uses a first mask made up of a non-woven fabric to close only a portion in which said conductive substance is to be deposited.

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8. The method according to Claim 6, wherein said step of forming a grounding protrusion uses a second mask wherein only a portion in which said conductive substance is to be deposited is opened and a residual portion thereof is closed.

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9. The method according to Claim 6, wherein said predetermined height is higher than a thickness of said solder resist film.

10. The method according to Claim 6, wherein said grounding protrusions are divided into a plurality of units in a portion where said signal transmission pattern is not formed.

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11. The method according to Claim 6, wherein said conductive substance is a solder cream.

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12. The method according to Claim 11, further comprising the step of hardening said solder cream by applying an ultraviolet ray and a heat onto said

PCB.

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